



68/2815  
#4/a  
10/29/03  
Surler

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Test, et al.

Docket No.: TI-30589

Serial No.: 09/817,696

Examiner: Richards, N. D.

Filed: 03/23/01

Art Unit: 2815

For: Wire Bonding Process for Copper-Metallized Integrated Circuits

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with  
the U.S. Postal Service as First Class Mail in an envelope addressed  
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

10-3-02

*Michael K. Skrehot*

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 07/03/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

RECEIVED  
OCT 10 2002  
TECHNOLOGY CENTER 2800